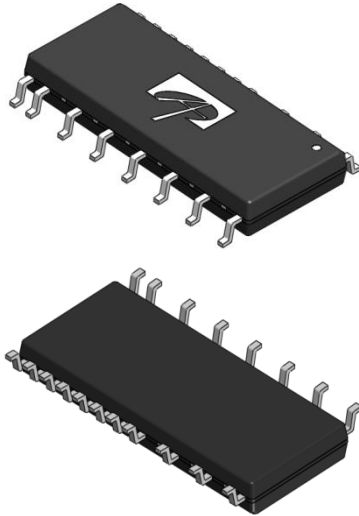# AIM702H50B

Intelligent Power Module

External View

Size: 18 x 7.5 x 2.5 mm

Green

Features

- 500V, $R_{DS(on)}$ = 4.0Ω (Max)
- Advanced MOSFET technology (αMOS2™) for motor drives
- Low loss and EMI
- 3-phase Inverter module including HVIC drivers
- Wide input interface (3-18V), Schmitt trigger receiver circuit (Active High)
- Built-in bootstrap diodes with integrated current-limiting resistor
- Control supply under-voltage lockout protection (UVLO)
- Over-temperature (OT) protection
- Temperature monitoring (V_{OT}) – 10kΩ resistor connection
- Isolation ratings of 1500Vrms/min

Applications

- AC 100~240Vrms class low power motor drives
- Fan motors

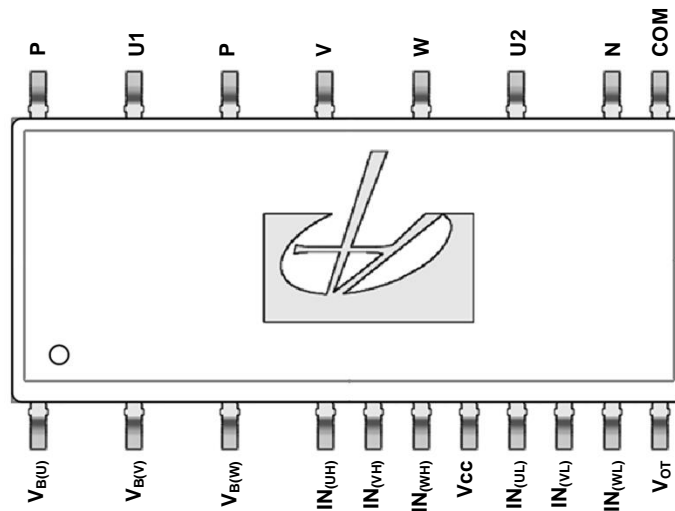## Internal Equivalent Circuit / Pin Configuration
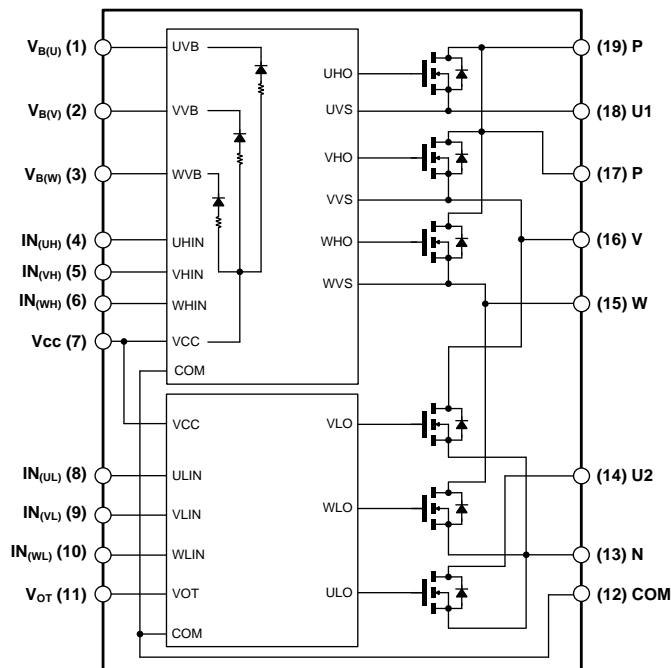
Ordering Information

Part Number	Temperature Range	Package	Description
AIM702H50B	-40°C to 150°C	IPM-7	N/A

AOS Green Products use reduced levels of Halogens, and are also RoHS compliant.
Please visit www.aosmd.com/media/AOSGreenPolicy.pdf for additional information.

Figure 1. Pin Configuration

Pin Description

Pin Number	Pin Name	Pin Function
1	$V_{B(U)}$	High-Side Bias Voltage for U-phase MOSFET Driving
2	$V_{B(V)}$	High-Side Bias Voltage for V-phase MOSFET Driving
3	$V_{B(W)}$	High-Side Bias Voltage for W-phase MOSFET Driving
4	$IN_{(UH)}$	Signal Input for High-Side U-phase
5	$IN_{(VH)}$	Signal Input for High-Side V-phase
6	$IN_{(WH)}$	Signal Input for High-Side W-phase
7	V_{CC}	Control Supply Voltage
8	$IN_{(UL)}$	Signal Input for Low-Side U-phase
9	$IN_{(VL)}$	Signal Input for Low-Side V-phase
10	$IN_{(WL)}$	Signal Input for Low-Side W-phase
11	V_{OT}	Voltage Output of LVIC Temperature
12	COM	Common Supply Ground
13	N	Negative DC-Link Input
14	U2	Output for U-phase (connect to U1)
15	W	Output for W-phase
16	V	Output for V-phase
17	P	Positive DC-Link Input
18	U1	Output for U-phase (connect to U2)
19	P	Positive DC-Link Input

Absolute Maximum Ratings (T$_J$=25°C, unless otherwise specified)

Symbol	Parameter	Conditions	Ratings	Units
Inverter				
BV$_{DSS}$	MOSFET Breakdown Voltage		500	V
I$_D$	MOSFET Drain Current (Continuous)	T$_C$=25°C	1.5	A
		T$_C$=80°C	0.85	A
I$_{DP}$	MOSFET Drain Current (Pulsed)	T$_C$=25°C, <100µs pulse width	2.25	A
P$_D$	Maximum Power Dissipation	T$_C$=25°C	8	W
T$_J$	Operating Junction Temperature		-40 to 150	°C
Control (Protection)				
V$_{CC}$	Control Supply Voltage	Applied between V$_{CC}$-COM	20	V
V$_{BS}$	High-Side Control Bias Voltage	Applied between V$_{B(U)}$-U, V$_{B(V)}$-V, V$_{B(W)}$-W	20	V
V$_{IN}$	Input Voltage	Applied between IN$_{(UH)}$, IN$_{(VH)}$, IN$_{(WH)}$, IN$_{(UL)}$, IN$_{(VL)}$, IN$_{(WL)}$-COM	V$_{CC}$±0.5	V
V$_{OT}$	Temperature Output	Applied between V$_{OT}$-COM	5±0.5	V
Thermal Resistance				
R$_{th(j-c)}$	Junction to Case Thermal Resistance	Each MOSFET	12.5	°C/W
R$_{th(j-a)}$	Junction to ambient thermal resistance	All operating condition	39	°C/W
Total System				
T$_C$	Module Case Operation Temperature	Measurement point of T$_C$ is provided in Figure 2	-30 to 125	°C
T$_{STG}$	Storage Temperature		-40 to 150	°C
V$_{ISO}$	Isolation Voltage	60Hz, sinusoidal, AC 1min, between connected all pins and heat sink plate	1500	V$_{rms}$
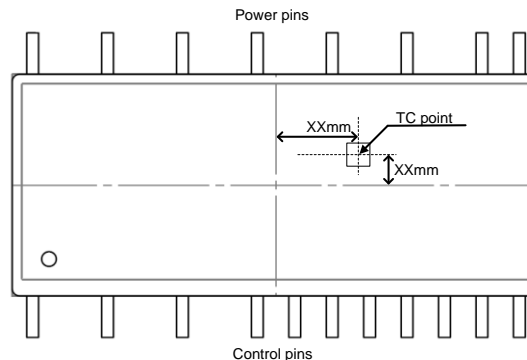
Figure 2. T$_C$ Measurement Point

Recommended Operation Conditions

| Symbol	Parameter	Conditions	Min.	Typ.	Max	Units
V$_{PN}$	Bus Supply Voltage	Applied between P-N	0	300	400	V
V$_{CC}$	Control Supply Voltage	Applied between V$_{CC}$-COM	13.5	15.0	16.5	V
V$_{BS}$	High-Side Bias Voltage	Applied between V$_{B(U)}$-U, V$_{B(V)}$-V, V$_{B(W)}$-W	13.5	15.0	16.5	V
dV$_{CC}$/dt, dV$_{BS}$/dt	Control Supply Variation		-1	-	1	V/us
t$_{dead}$	Arm Shoot-Through Blocking Time	For each input signal	1.5	-	-	µs
f$_{PWM}$	PWM Input Frequency	-40°C < T$_J$ < 150°C	-	16	-	kHz
PW$_{IN(ON)}$	Minimum Input Pulse Width [1]		0.7	-	-	µs
PW$_{IN(OFF)}$			0.7	-	-	µs

Note:

1. IPM may not respond if the input pulse width is less than PW$_{IN(ON)}$, PW$_{IN(OFF)}$.

Electrical Characteristics (T$_J$=25°C, unless otherwise specified)

| Symbol	Parameter	Conditions		Min.	Typ.	Max	Units
Inverter							
I$_{DSS}$	Drain-Source Leakage Current	V$_{IN}$=0V, V$_{DS}$=500V		-	-	100	µA
R$_{DS(on)}$	Drain-Source On-State Resistance	V$_{CC}$=V$_{BS}$=15V, V$_{IN}$=5V	I$_D$=0.75A	-	3.2	4.0	Ω
V$_{SD}$	MOSFET Body Diode Forward Voltage	V$_{CC}$=V$_{BS}$=15V, V$_{IN}$=0	I$_{SD}$=0.75A	-	0.8	1.2	V
t$_{OFF}$	Switching Times	V$_{PN}$=300V, V$_{CC}$=V$_{BS}$=15V I$_D$=0.75A, V$_{IN}$=0V↔5V Inductive load (high-side)		-	800	-	ns
t$_f$				-	70	-	ns
t$_{ON}$				-	800	-	ns
t$_r$				-	80	-	ns
t$_{rr}$				-	160	-	ns
Control (Protection)							
I$_{QCC}$	Quiescent V$_{CC}$ Supply Current	V$_{CC}$=15V, IN$_{(UL, VL, WL)}$=0V	V$_{CC}$-COM	-	-	1.5	mA
I$_{QBS}$	Quiescent V$_{BS}$ Supply Current	V$_{BS}$=15V, IN$_{(UH, VH, WH)}$=0V	V$_{B(U)}$-U, V$_{B(V)}$-V, V$_{B(W)}$-W	-	-	0.3	mA
UV$_{CCT}$	Supply Circuit Under-Voltage Protection	Trip Level		10.3	11.4	12.5	V
UV$_{CCR}$		Reset Level		10.8	11.9	13.0	V
UV$_{BST}$		Trip Level		9.0	10.0	11.0	V
UV$_{BSR}$		Reset Level		10.0	11.0	12.0	V
V$_{OT}$	Temperature Output	Pull-down R=10kΩ [(2)]	LVIC temperature=90°C	2.65	2.78	2.92	V
			LVIC temperature=25°C	0.80	1.05	1.30	V
OT$_T$	Over-Temperature Protection [(3)]	V$_{CC}$=15V, Detect LVIC Temperature	Trip Level	110	130	150	°C
OT$_{HYS}$			Hysteresis of Trip Reset	-	30	-	°C
I$_{IN}$	Input Current	V$_{IN}$=5V		-	650	850	µA
V$_{th(on)}$	ON Threshold Voltage	Applied between IN$_{(UH)}$, IN$_{(VH)}$, IN$_{(WH)}$, IN$_{(UL)}$, IN$_{(VL)}$, IN$_{(WL)}$ –COM		-	-	2.5	V
V$_{th(off)}$	OFF Threshold Voltage			0.8	-	-	V
Bootstrap Diode							
V$_{RRM}$	Maximum Repetitive Reverse Voltage	I$_F$=10mA including voltage drop by limiting resistor		600	-	-	V
V$_{F(BSD)}$	Bootstrap Diode Forward Voltage			-	5.0	-	V
R$_{BSD}$	Bootstrap Diode Equivalent Resistance			-	500	-	Ω

Note:

2. The IPM does not shutdown MOSFETs and output fault signal automatically when temperature rises excessively. When temperature exceeds the protective level that the user defined, the controller (MCU) should stop the IPM. Temperature of LVIC vs. V$_{OT}$ output characteristics is described in Figure 3.

3. When the LVIC temperature exceeds OT Trip temperature level (OT$_T$), OT protection is triggered and fault outputs.
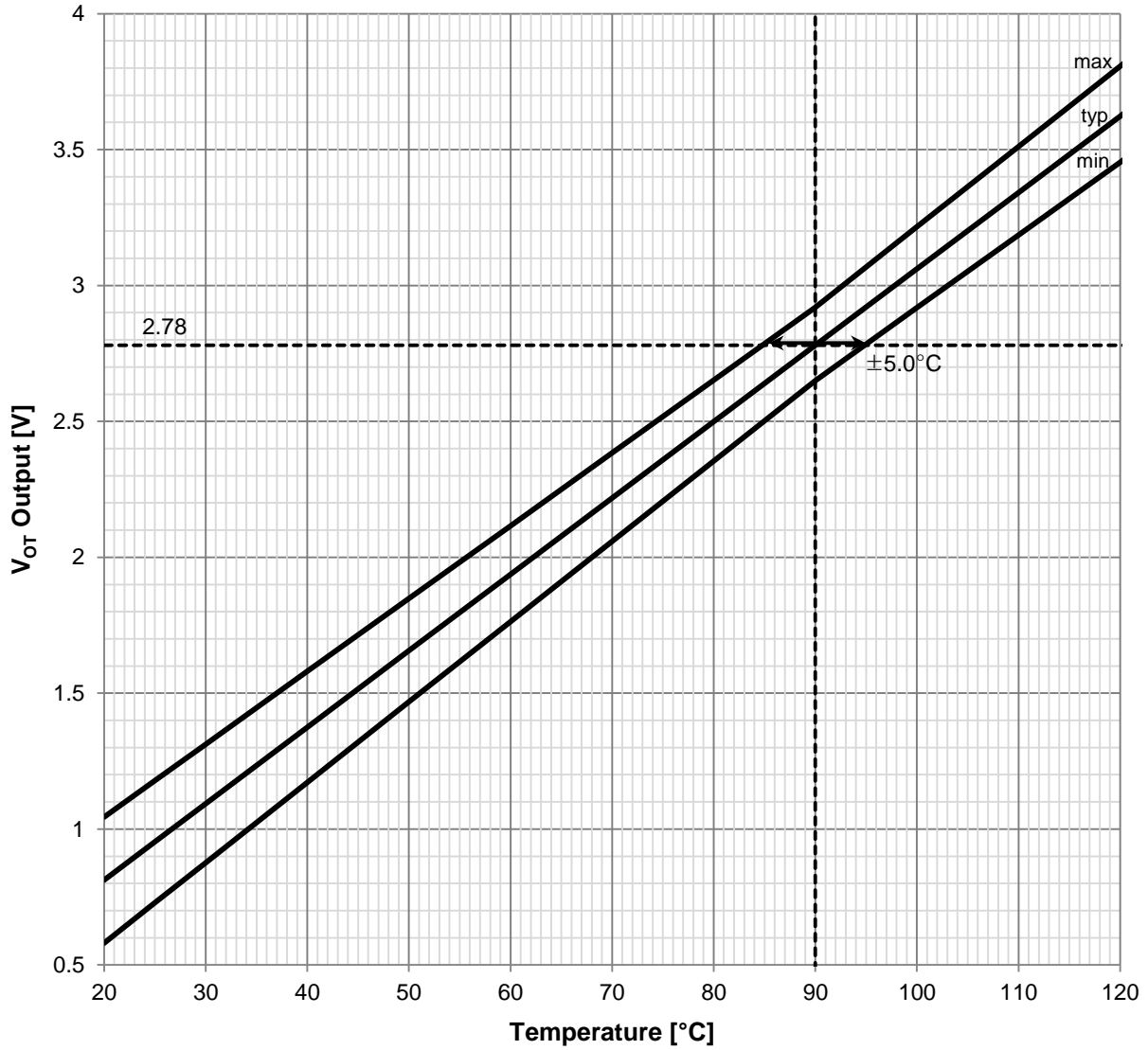
Figure 3. Temperature of LVIC vs. V$_{OT}$ Output Characteristics
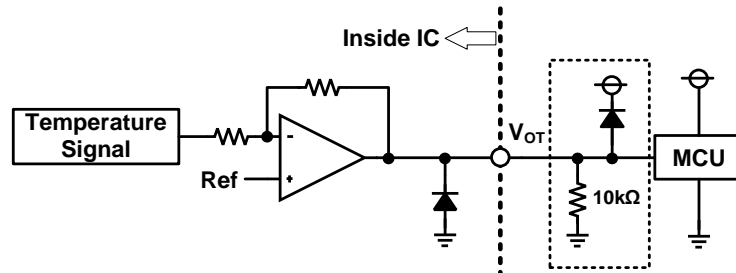
(1) Connect 10kΩ to V$_{OT}$ pin if temperature monitoring function is utilized; otherwise if the V$_{OT}$ pin is left unconnected, the internal over-temperature shutdown function is used instead.

(2) In the case of using V$_{OT}$ with low voltage controller like 3.3V MCU, V$_{OT}$ output might exceed control supply voltage 3.3V when temperature rises excessively. If system uses low voltage controller, it is recommended to insert a clamp diode between control supply of the controller and V$_{OT}$ output for preventing over voltage destruction.

Figure 4. V$_{OT}$ Output Circuit

Time Charts of the IPM Protective Function
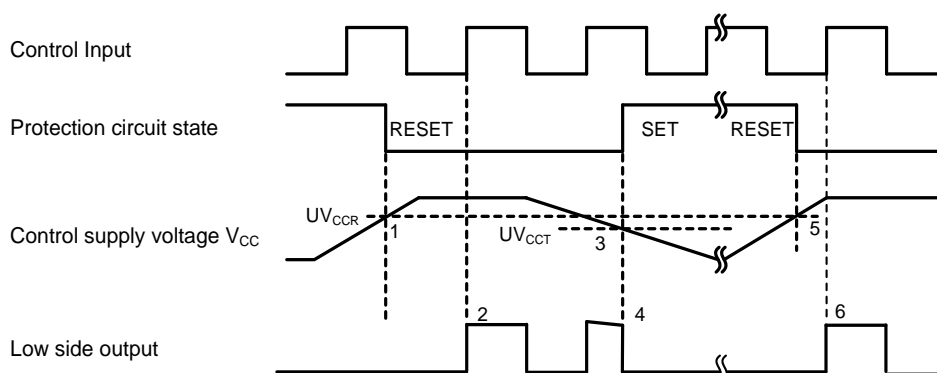

(1) Control supply voltage V_{CC} exceeds under-voltage reset level (UV_{CCR}), but MOSFETs turn on by next ON signal (L→H).

(2) Normal operation: MOSFETs turn-on and output current.

(3) V_{CC} level drops to under-voltage trip level (UV_{CCT}).

(4) All low-side MOSFETs turn off regardless of control input condition.

(5) V_{CC} level reaches UV_{CCR}.

(6) Normal operation: MOSFETs turn on and output current.

**Figure 5. Under-Voltage Protection (Low-side, UV_{CC})**
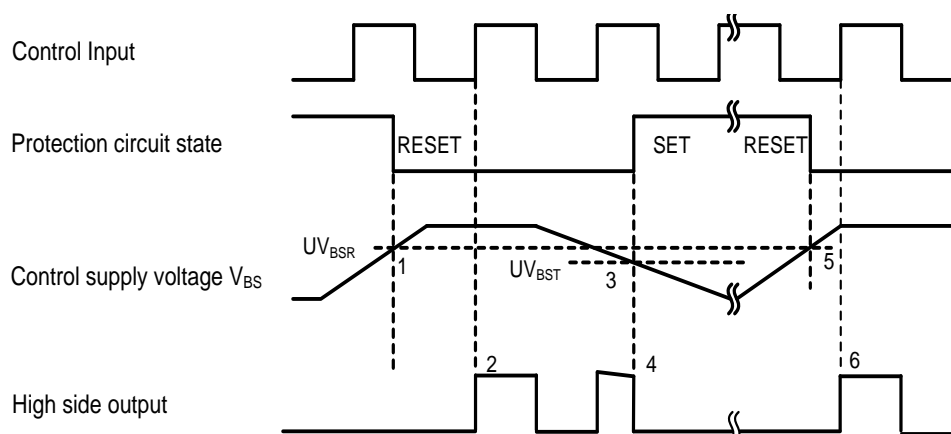
(1) Control supply voltage V_{BS} rises. After the voltage reaches under-voltage reset level (UV_{BSR}), MOSFETs turn on by next ON signal (L→H).

(2) Normal operation: MOSFETs turn on and output current.

(3) V_{BS} level drops to under-voltage trip level (UV_{BST}).

(4) All high-side MOSFETs turn off regardless of control input condition.

(5) V_{BS} level reaches UV_{BSR}.

(6) Normal operation: MOSFETs turn on and output current.

**Figure 6. Under-Voltage Protection (High-side, UV_{BS})**
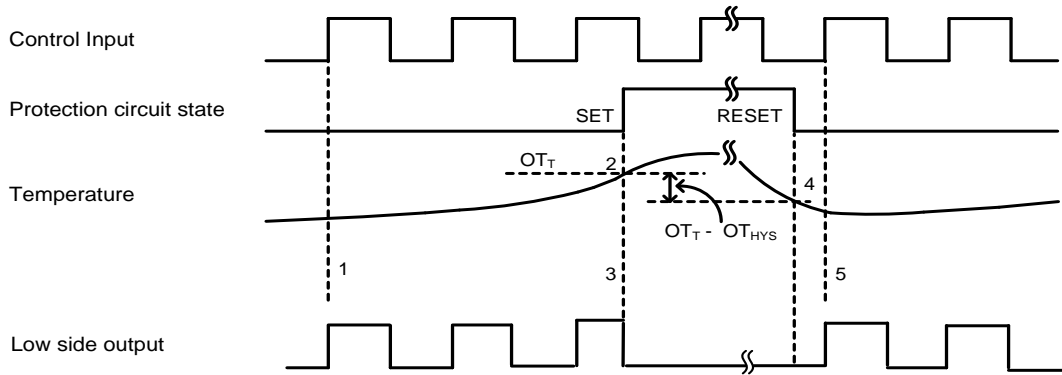
(1) Normal operation: MOSFETs turn on and output current.

(2) LVIC temperature exceeds over-temperature trip level (OT_T).

(3) All low-side MOSFETs turn off regardless of control input condition.

(4) LVIC temperature drops to over-temperature reset level (OT_T-OT_{HYS}).

(5) Normal operation: MOSFETs turn on by the next ON signal (L→H).

Figure 7. Over-Temperature Protection (Low-side, Detecting LVIC Temperature)

(a) Turn-on Waveform

(b) Turn-off Waveform
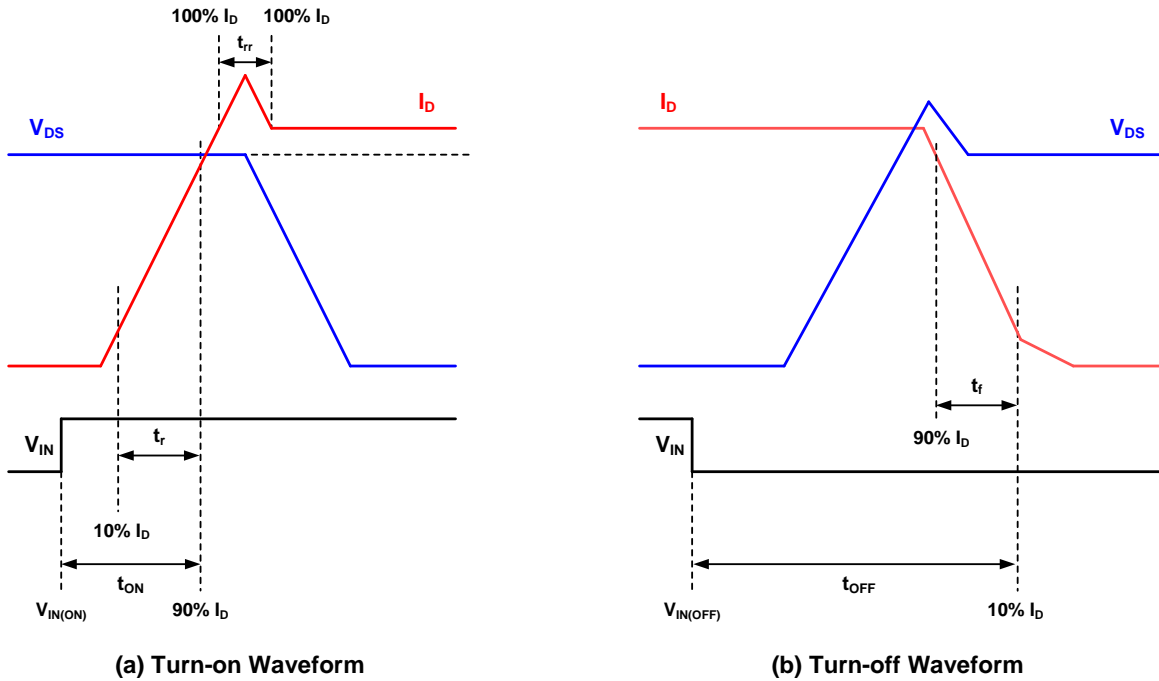
Figure 8. Switching Times Definition

Example of Application Circuit
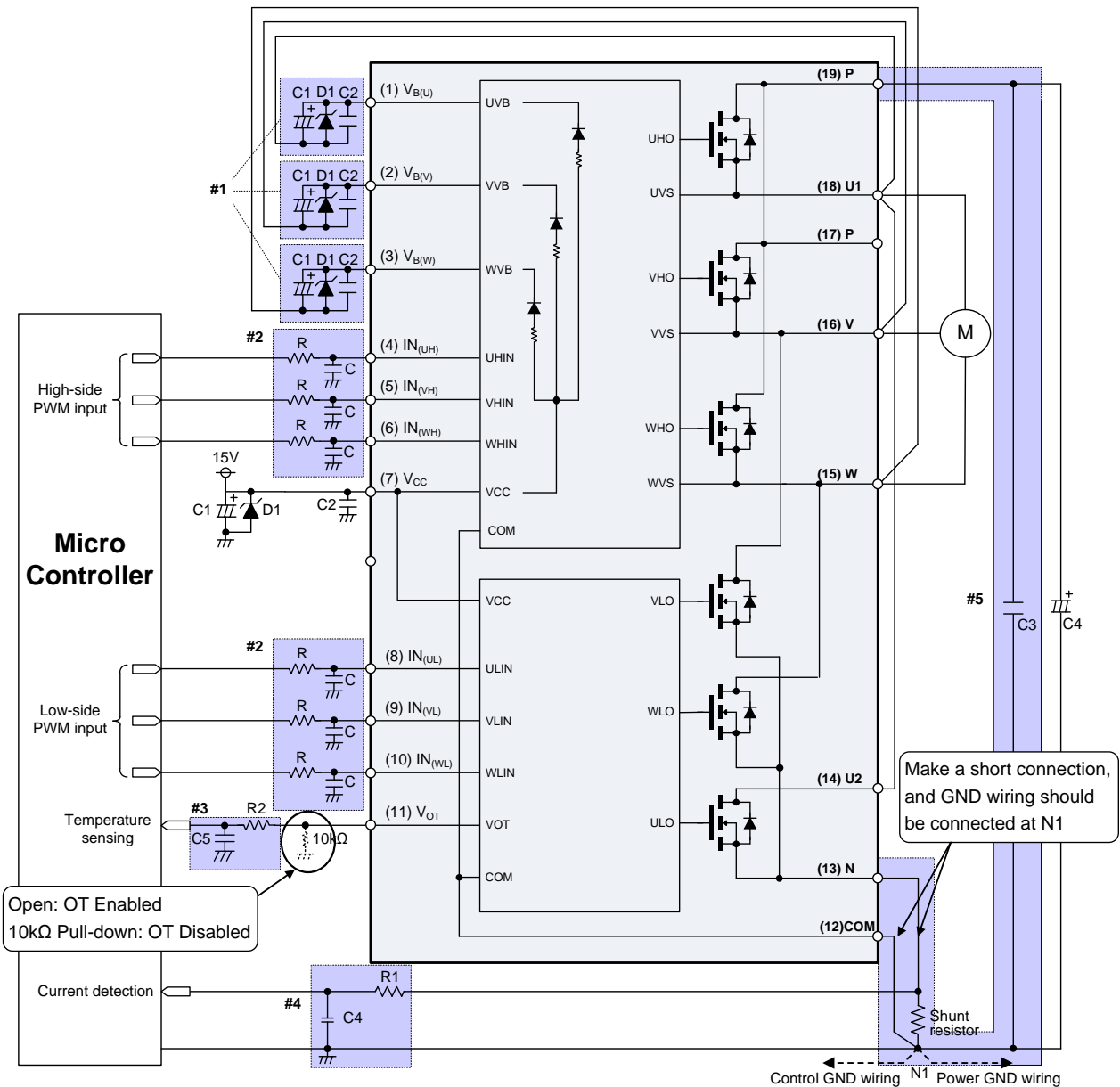
Recommended Component Values:
(#1) C1:1~3.3µF, C2:100nF, D1:20V   (#2) R:100Ω, C:1nF   (#3) R2:2kΩ, C5:10nF
(#4) R1:1kΩ, C4:2nF   (#5) C3:0.1~0.22µF

(1) If the control GND is connected with the power GND by common broad pattern, it may cause malfunction by power GND fluctuation.
It is recommended to connect the control GND and power GND at a point (N1), near the terminal of shunt resistor.

(2) A zener diode D1 (20V/1W) is recommended between each pair of control supply pins to prevent surge destruction.

(3) Prevention of surge destruction can further be improved by placing the bus capacitor as close to pin P and N1 as possible.
Generally a 0.1~0.22µF snubber capacitor C3 between the P-N1 terminals is recommended.

(4) When the current detection function is utilized by using the shunt resistor, the RC filter (R1 and C4) needs to be inserted to avoid the voltage spike noise in the current detection circuit. C4 should be placed as close to the controller as possible.

(5) Tight tolerance and temperature-compensated components are also recommended when selecting the R2*C5 filter for V_{OT}. The R2*C5 time constant should be set such that V_{OT} is immune to noise. Recommended values of R2 and C5 are 2kΩ and 10nF.

(6) It is recommended that all capacitors are mounted as close to the IPM as possible. (C1: electrolytic type with good temperature and frequency characteristics. C2: ceramic type with 0.1µF, good temperature, frequency and DC bias characteristics).

(7) To prevent malfunction, the layout to each input should be as short as possible. When using the RC coupling circuit (R: 100Ω, C: 1nF), place it as close to the IPM input pins as possible, and make sure the input signal levels meet the required turn-on and turn-off threshold voltages.
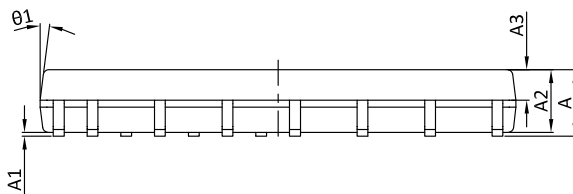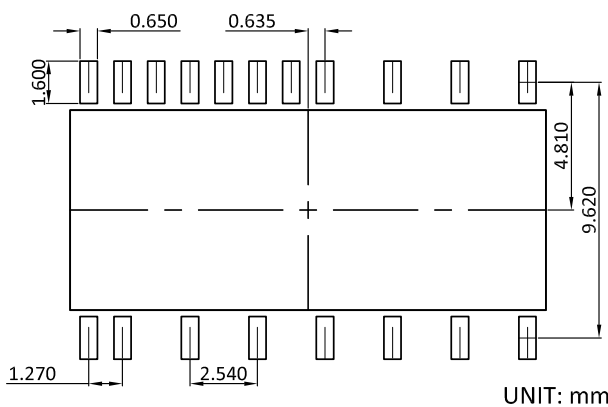
Package Dimensions, IPM-7
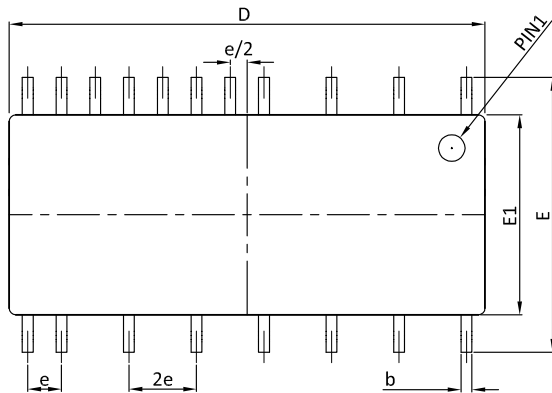
TOP VIEW
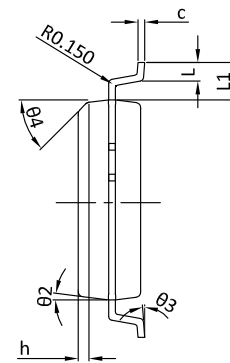
SIDE VIEW

SIDE VIEW

LAND PATTERN RECOMMENDATIONS

UNIT: mm

SYMBOLS	DIMENSION IN MILLIMETRES			DIMENSION IN INCHS		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	2.304	2.504	2.704	0.091	0.099	0.106
A1	0.050	0.150	0.250	0.002	0.006	0.010
A2	2.254	2.354	2.454	0.089	0.093	0.097
A3	1.050	1.150	1.250	0.041	0.045	0.049
D	17.800	17.900	18.000	0.701	0.705	0.709
E	10.140	10.340	10.540	0.399	0.407	0.415
E1	7.420	7.520	7.620	0.292	0.296	0.300
L	0.505	0.705	0.905	0.020	0.028	0.036
L1	1.210	1.410	1.610	0.048	0.056	0.063
e	1.270TYP.			0.050TYP.		
b	0.410TYP.			0.016TYP.		
c	0.254TYP.			0.010TYP.		
θ1	7°TYP.			7°TYP.		
θ2	7°TYP.			7°TYP.		
θ3	0°	---	8°	0°	---	8°
θ4	45°TYP.			45°TYP.		
h	0.381TYP.			0.015TYP.		

NOTES
1. PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS, MOLD FLASH SHOULD BE LESS THAN 6 MIL.
2. TOLERANCE 0.100 MILLIMETERS UNLESS OTHERWISE SPECIFIED.
3. CONTROLLING DIMENSION IS MILLIMETER, CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

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